

2.5-V 460-kbps RS-232 TRANSCEIVER WITH ± 15 -kV ESD PROTECTION

Check for Samples: [MAX3318E](#)

FEATURES

- **ESD Protection for RS-232 I/O Pins**
 - ± 15 kV (Human-Body Model)
 - ± 8 kV (IEC 61000-4-2, Contact Discharge)
 - ± 15 kV (IEC 61000-4-2, Air-Gap Discharge)
- **300- μ A Operating Supply Current**
- **1- μ A Low-Power Standby (With Receivers Active) Mode**
- **Designed to Transmit at a Data Rate of 460 kbps**
- **Auto-Power-Down Plus Option Features**
Flexible Power-Saving Mode
- **Operates From a Single 2.25-V to 3-V V_{cc} Supply**

APPLICATIONS

- **Battery-Powered Systems**
- **PDAs**
- **Cellular Phones**
- **Notebooks**
- **Hand-Held Equipment**
- **Pagers**

DESCRIPTION

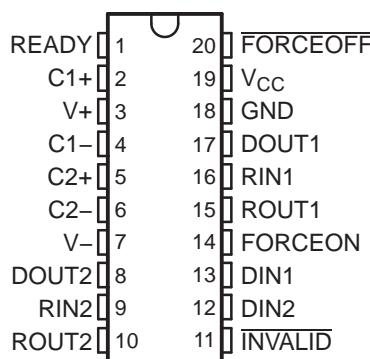
The MAX3318E is a dual-driver, dual-receiver, RS-232-compatible transceiver. The device features auto-power-down plus and enhanced electrostatic discharge (ESD) protection integrated into the chip. Driver output and receiver input are protected to ± 15 kV using the IEC 61000-4-2 Air-Gap Discharge method, ± 8 kV using the IEC 61000-4-2 Contact Discharge method, and ± 15 kV using the Human-Body Model (HBM).

The device operates at a data rate of 460 kbps. The transceiver has a proprietary low-dropout driver output stage, enabling RS-232-compatible operation from a 2.25-V to 3-V supply with a dual charge pump. The charge pump requires only four 0.1- μ F capacitors and features a logic-level output (READY) that asserts when the charge pump is regulating and the device is ready to begin transmitting.

The MAX3318E achieves a 1- μ A supply current using the auto-power-down feature. This device automatically enters a low-power power-down mode when the RS-232 cable is disconnected or the drivers of the connected peripherals are inactive for more than 30 s. The device turns on again when it senses a valid transition at any driver or receiver input. Auto power down saves power without changes to the existing BIOS or operating system.

This device is available in two space-saving packages: 20-pin SSOP and 20-pin TSSOP.

DB OR PW PACKAGE
(TOP VIEW)



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

 This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

 ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

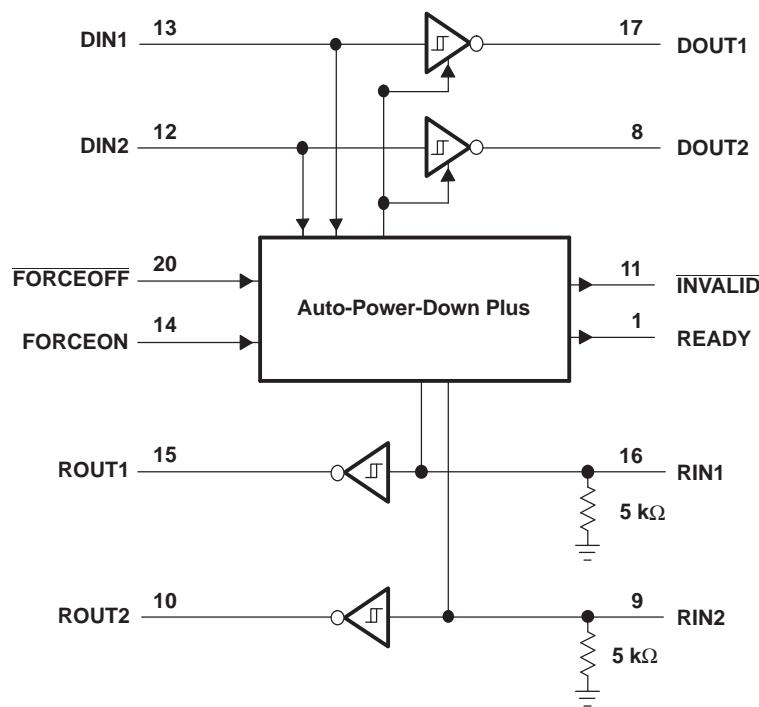
DETAILED DESCRIPTION

Flexible control options for power management are featured when the serial port and driver inputs are inactive. The auto-power-down plus feature functions when **FORCEON** is low and **FORCEOFF** is high. During this mode of operation, if the device does not sense valid signal transitions on all receiver and driver inputs for approximately 30 s, the built-in charge pump and drivers are powered down, reducing the supply current to 1 μ A. By disconnecting the serial port or placing the peripheral drivers off, auto-power-down plus can be disabled when **FORCEON** and **FORCEOFF** are high. With auto-power-down plus enabled, the device activates automatically when a valid signal is applied to any receiver or driver input. **INVALID** is high (valid data) if any receiver input voltage is greater than 2.7 V or less than -2.7 V, or has been between -0.3 V and 0.3 V for less than 30 μ s (typical number). **INVALID** is low (invalid data) if all receiver input voltage are between -0.3 V and 0.3 V for more than 30 μ s (typical number).

FUNCTION TABLE⁽¹⁾

INPUT CONDITIONS				OUTPUT STATES				OPERATING MODE
FORCEON	FORCEOFF	RECEIVER OR DRIVER EDGE WITHIN 30 s	VALID RS-232 LEVEL PRESENT AT RECEIVER	DRIVER	RECEIVER	INVALID	READY	
Auto-Power-Down Plus Conditions								
H	H	No	No	Active	Active	L	H	Normal operation, auto-power-down plus disabled
H	H	No	Yes	Active	Active	H	H	Normal operation, auto-power-down plus disabled
L	H	Yes	No	Active	Active	L	H	Normal operation, auto-power-down plus enabled
L	H	Yes	Yes	Active	Active	H	H	Normal operation, auto-power-down plus enabled
L	H	No	No	Z	Active	L	L	Power down, auto-power-down plus enabled
L	H	No	Yes	Z	Active	H	L	Power down, auto-power-down plus enabled
X	L	X	No	Z	Active	L	L	Manual power down
X	L	X	Yes	Z	Active	H	L	Manual power down
Auto-Power-Down Conditions								
INVALID	INVALID	X	No	Z	Active	L	L	Power down, auto power down enabled
INVALID	INVALID	X	Yes	Active	Active	H	H	Normal operation, auto power down enabled

(1) H = high level, L = low level, X = irrelevant, Z = high impedance

LOGIC DIAGRAM (POSITIVE LOGIC)

TERMINAL FUNCTIONS

TERMINAL			DESCRIPTION
NAME	NO.		
C1+	2		Positive voltage-doubler charge-pump capacitor
C1-	4		Negative voltage-doubler charge-pump capacitor
C2+	5		Positive inverting charge-pump capacitor
C2-	6		Negative inverting charge-pump capacitor
DIN	12, 13		CMOS driver inputs
DOUT	8, 17		RS-232 driver outputs
FORCEOFF	20		Force-off input, active low. Drive low to power down transmitters and charge pump. This overrides auto power down and FORCEON (see Function Table).
FORCEON	14		Force-on input, active high. Drive high to override auto power down, keeping transmitters on (FORCEOFF must be high) (see Function Table).
GND	18		Ground
INVALID	11		Valid signal detector output, active low. A logic high indicates that a valid RS-232 level is present on a receiver input.
READY	1		Ready to transmit output, active high. READY is enabled high when V- goes below -3.5 V and the device is ready to transmit.
RIN	9, 16		RS-232 receiver inputs
ROUT	10, 15		CMOS receiver outputs
V+	3		$2 \times V_{CC}$ generated by the charge pump
V-	7		$-2 \times V_{CC}$ generated by the charge pump
V _{CC}	19		2.25-V to 3-V single-supply voltage

Absolute Maximum Ratings⁽¹⁾

over operating free-air temperature range (unless otherwise noted)

		MIN	MAX	UNIT
V_{CC} to GND		−0.3	6	V
V_+ to GND ⁽²⁾		−0.3	7	V
V_- to GND ⁽²⁾		−7	0.3	V
$V_+ + IV$ −I ⁽²⁾			13	V
Input voltage	DIN, FORCEON, FORCEOFF to GND	−0.3	6	V
	RIN to GND		±25	
Output voltage	DOUT to GND		±13.2	V
	ROUT, INVALID, READY to GND	−0.3	$V_{CC} + 0.3$	
Short-circuit duration	DOUT to GND		Continuous	
Continuous power dissipation ($T_A = 70^\circ\text{C}$)	16-pin SSOP (derate 7.14 mW/°C above 70°C)		571	mW
	20-pin SSOP (derate 8 mW/°C above 70°C)		640	
	20-pin TSSOP (derate 7 mW/°C above 70°C)		559	
Storage temperature range		−65	150	°C
Lead temperature (soldering, 10 s)			300	°C

(1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

(2) V_+ and V_- can have maximum magnitudes of 7 V, but their absolute difference cannot exceed 13 V.

Recommended Operating Conditions

See Figure 4

		MIN	NOM	MAX	UNIT
Supply voltage		2.25	2.5	3	V
V_{IH} Driver and control high-level input voltage	DIN, FORCEOFF, FORCEON	$V_{CC} = 2.5\text{ V to }3\text{ V}$	$0.7 \times V_{CC}$	5.5	V
V_{IL} Driver and control low-level input voltage	DIN, FORCEOFF, FORCEON	$V_{CC} = 2.5\text{ V to }3\text{ V}$	0	$0.3 \times V_{CC}$	V
V_I Receiver input voltage			−25	25	V
T_A Operating free-air temperature	MAX3318EC		0	70	°C
	MAX3318EI		−40	85	

Supply Current Section Electrical Characteristics

$V_{CC} = 2.25 \text{ V to } 3 \text{ V}$, $C1-C4 = 0.1 \mu\text{F}$, $T_A = T_{MIN} \text{ to } T_{MAX}$ (unless otherwise noted)

PARAMETER	TEST CONDITIONS	MIN	TYP ⁽¹⁾	MAX	UNIT
DC Characteristics ($V_{CC} = 2.5 \text{ V}$, $T_A = 25^\circ\text{C}$)					
Auto-power-down plus supply current	FORCEON = GND, FORCEOFF = V_{CC} , All RIN and DIN idle		1	10	μA
Auto-power-down supply current	FORCEOFF = GND		1	10	μA
Supply current	FORCEON = FORCEOFF = V_{CC} , No load		0.3	2	mA

(1) Typical values are at $V_{CC} = 2.5 \text{ V}$, $T_A = 25^\circ\text{C}$.

ESD Protection

PARAMETER	TEST CONDITIONS	TYP	UNIT
RIN, DOUT	HBM	± 15	kV
	IEC 61000-4-2 Air-Gap Discharge method	± 15	
	IEC 61000-4-2 Contact Discharge method	± 8	

Driver Section Electrical Characteristics

over recommended ranges of supply voltage and operating free-air temperature,
 $V_{CC} = 2.25 \text{ V to } 3 \text{ V}$, $C1-C4 = 0.1 \mu\text{F}$, $T_A = T_{MIN} \text{ to } T_{MAX}$ (unless otherwise noted) (see [Figure 4](#))

PARAMETER	TEST CONDITIONS	MIN	TYP ⁽¹⁾	MAX	UNIT
Driver input hysteresis			0.3		V
Input leakage current	FORCEON, DIN, FORCEOFF		± 0.01	± 1	μA
Output voltage swing	All driver outputs loaded with $3 \text{ k}\Omega$ to ground	± 3.7	± 4		V
Output resistance	$V_{CC} = 0$, Driver output = $\pm 2 \text{ V}$	300	10M		Ω
Output short-circuit current ⁽²⁾			± 25	± 60	mA
Output leakage current	$V_{CC} = 0$ or $2.25 \text{ V to } 3 \text{ V}$, $V_{OUT} = \pm 12 \text{ V}$, Drivers disabled		± 25		μA

(1) Typical values are at $V_{CC} = 2.5 \text{ V}$, $T_A = 25^\circ\text{C}$.

(2) Short-circuit durations should be controlled to prevent exceeding the device absolute power dissipation ratings, and not more than one output should be shorted at a time.

Driver Section Switching Characteristics

over recommended ranges of supply voltage and operating free-air temperature,
 $V_{CC} = 2.25 \text{ V to } 3 \text{ V}$, $C1-C4 = 0.1 \mu\text{F}$, $T_A = T_{MIN} \text{ to } T_{MAX}$ (unless otherwise noted) (see [Figure 1](#))

PARAMETER	TEST CONDITIONS	MIN	TYP ⁽¹⁾	MAX	UNIT
Maximum data rate	$R_L = 3 \text{ k}\Omega$, $C_L = 1000 \text{ pF}$, One transmitter switching	460			kbps
$ t_{PHL} - t_{PLH} $ Driver skew ⁽²⁾			100		ns
Transition-region slew rate	$V_{CC} = 2.5 \text{ V}$, $T_A = 25^\circ\text{C}$, $R_L = 3 \text{ k}\Omega$ to $7 \text{ k}\Omega$, Measured from $3 \text{ V to } -3 \text{ V}$ or $-3 \text{ V to } 3 \text{ V}$, $C_L = 150 \text{ pF}$ to 2500 pF	4		30	$\text{V}/\mu\text{s}$

(1) Typical values are at $V_{CC} = 2.5 \text{ V}$, $T_A = 25^\circ\text{C}$.

(2) Pulse skew is defined as $|t_{PLH} - t_{PHL}|$ of each channel of the same device.

Receiver Section Electrical Characteristics

over recommended ranges of supply voltage and operating free-air temperature,
 $V_{CC} = 2.25 \text{ V to } 3 \text{ V}$, $C1\text{--}C4 = 0.1 \mu\text{F}$, $T_A = T_{MIN} \text{ to } T_{MAX}$ (unless otherwise noted) (see [Figure 4](#))

PARAMETER	TEST CONDITIONS	MIN	TYP ⁽¹⁾	MAX	UNIT
Input voltage range			-25	25	V
Input threshold low	$T_A = 25^\circ\text{C}$			$0.3 \times V_{CC}$	V
Input threshold high	$T_A = 25^\circ\text{C}$		$0.7 \times V_{CC}$		V
Input hysteresis				0.3	V
Input resistance	$T_A = 25^\circ\text{C}$	3	5	7	$\text{k}\Omega$
Output leakage current			± 0.05	± 10	μA
Output voltage low	$I_{OUT} = 0.5 \text{ mA}$			$0.1 \times V_{CC}$	V
Output voltage high	$I_{OUT} = -0.5 \text{ mA}$		$0.9 \times V_{CC}$		V

(1) Typical values are at $V_{CC} = 2.5 \text{ V}$, $T_A = 25^\circ\text{C}$.

Receiver Section Switching Characteristics

over recommended ranges of supply voltage and operating free-air temperature,
 $V_{CC} = 2.25 \text{ V to } 3 \text{ V}$, $C1\text{--}C4 = 0.1 \mu\text{F}$, $T_A = T_{MIN} \text{ to } T_{MAX}$ (unless otherwise noted) (see [Figure 4](#))

PARAMETER	TEST CONDITIONS	TYP ⁽¹⁾	UNIT
t_{PHL}	Receiver propagation delay $R_{IN} \text{ to } R_{OUT}$, $C_L = 150 \text{ pF}$	0.175	μs
t_{PLH}		0.175	
$ t_{PHL} - t_{PLH} $	Receiver skew ⁽²⁾	50	ns

(1) Typical values are at $V_{CC} = 2.5 \text{ V}$, $T_A = 25^\circ\text{C}$.

(2) Pulse skew is defined as $|t_{PLH} - t_{PHL}|$ of each channel of the same device.

Auto-Power-Down Plus Section Electrical Characteristics

over recommended ranges of supply voltage and operating free-air temperature,
 $V_{CC} = 2.25 \text{ V to } 3 \text{ V}$, $C1\text{--}C4 = 0.1 \mu\text{F}$, $T_A = T_{MIN} \text{ to } T_{MAX}$ (unless otherwise noted) (see [Figure 4](#))

PARAMETER	TEST CONDITIONS	MIN	MAX	UNIT
Receiver input threshold to <u>INVALID</u> high	Positive threshold		2.7	V
	Negative threshold		-2.7	
Receiver input threshold <u>INVALID</u> low		-0.3	0.3	V
<u>INVALID</u> , READY voltage low	$I_{OUT} = 0.5 \text{ mA}$		$0.1 \times V_{CC}$	V
<u>INVALID</u> , READY voltage high	$I_{OUT} = -0.5 \text{ mA}$		$0.8 \times V_{CC}$	V

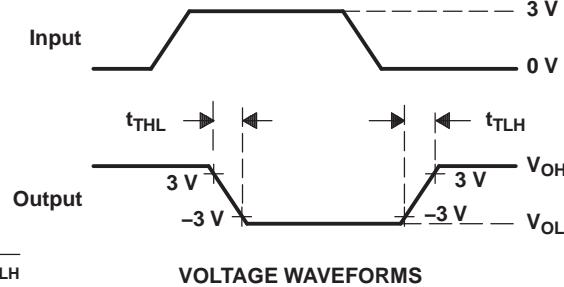
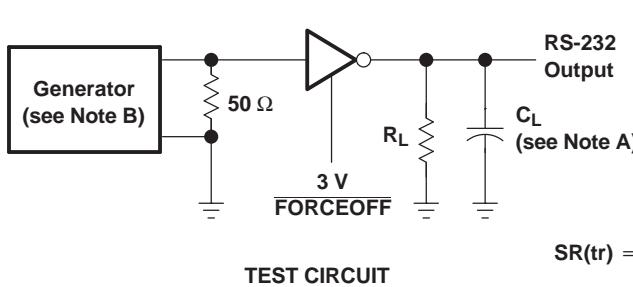
Auto-Power-Down Plus Section Switching Characteristics

over recommended ranges of supply voltage and operating free-air temperature,
 $V_{CC} = 2.25 \text{ V to } 3 \text{ V}$, $C1\text{--}C4 = 0.1 \mu\text{F}$, $T_A = T_{MIN} \text{ to } T_{MAX}$ (unless otherwise noted) (see [Figure 4](#))

PARAMETER	TEST CONDITIONS	MIN	TYP ⁽¹⁾	MAX	UNIT
t_{INVH}	Receiver positive or negative threshold to <u>INVALID</u> high $V_{CC} = 2.5 \text{ V}$		1		μs
t_{INVL}	Receiver positive or negative threshold to <u>INVALID</u> low $V_{CC} = 2.5 \text{ V}$		30		μs
t_{WU}	Receiver or driver edge to driver enabled $V_{CC} = 2.5 \text{ V}$		100		μs
$t_{AUTOPRDN}$	Receiver or driver edge to driver shutdown $V_{CC} = 2.5 \text{ V}$	15	30	60	s

(1) Typical values are at $V_{CC} = 2.5 \text{ V}$, $T_A = 25^\circ\text{C}$.

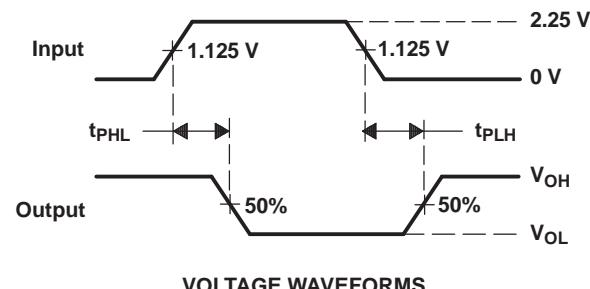
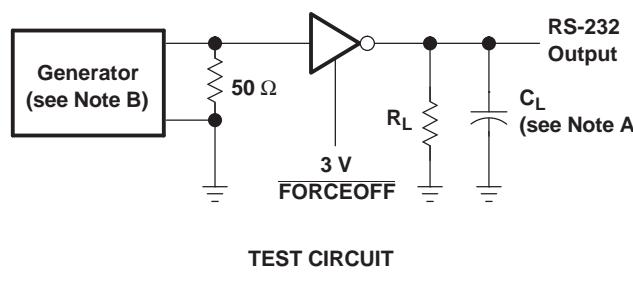
PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and jig capacitance.

B. The pulse generator has the following characteristics: PRR = 250 kbit/s, $Z_O = 50 \Omega$, 50% duty cycle, $t_r \leq 10 \text{ ns}$, $t_f \leq 10 \text{ ns}$.

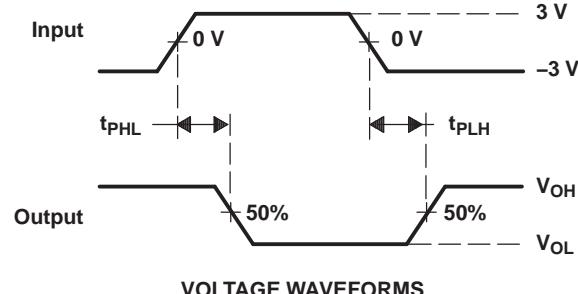
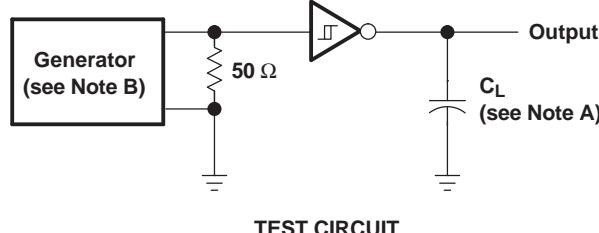
Figure 1. Driver Slew Rate



NOTES: A. C_L includes probe and jig capacitance.

B. The pulse generator has the following characteristics: PRR = 250 kbit/s, $Z_O = 50 \Omega$, 50% duty cycle, $t_r \leq 10 \text{ ns}$, $t_f \leq 10 \text{ ns}$.

Figure 2. Driver Pulse Skew

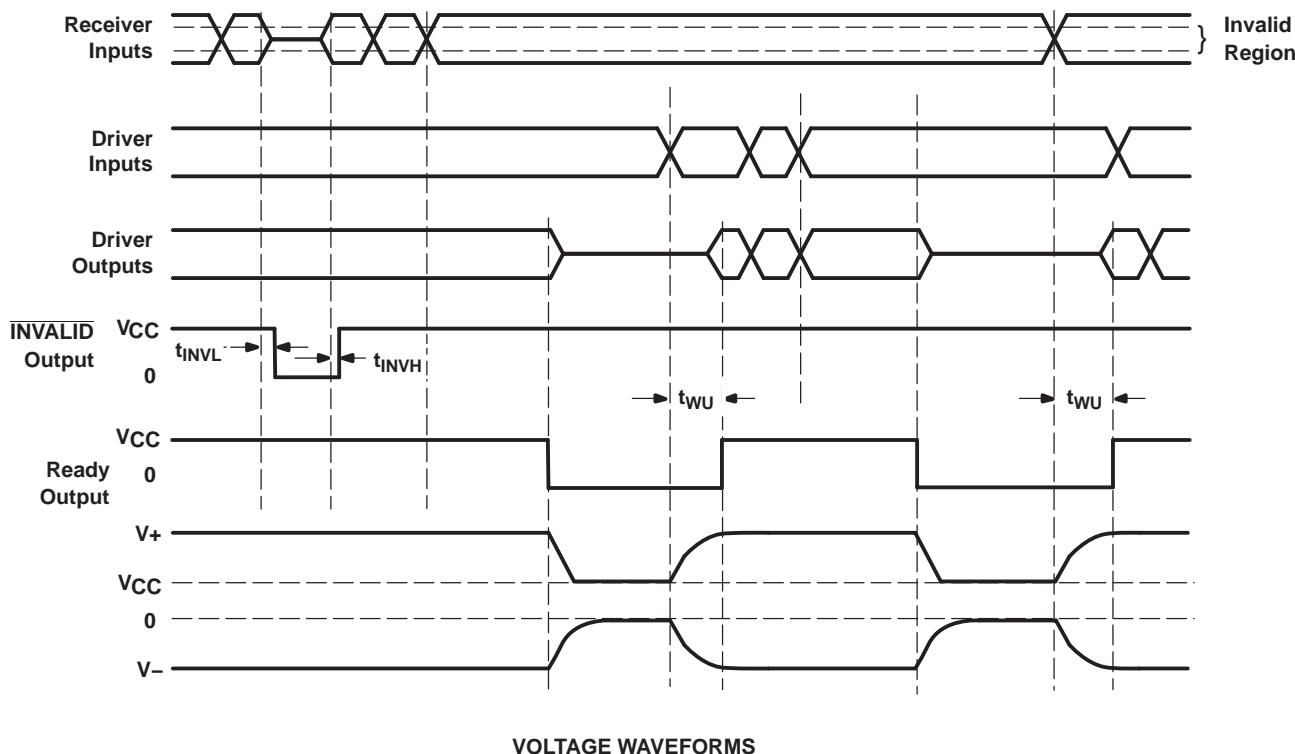


NOTES: A. C_L includes probe and jig capacitance.

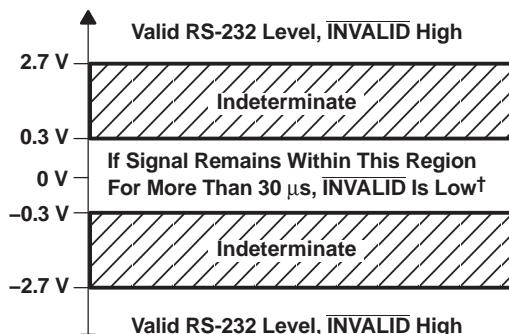
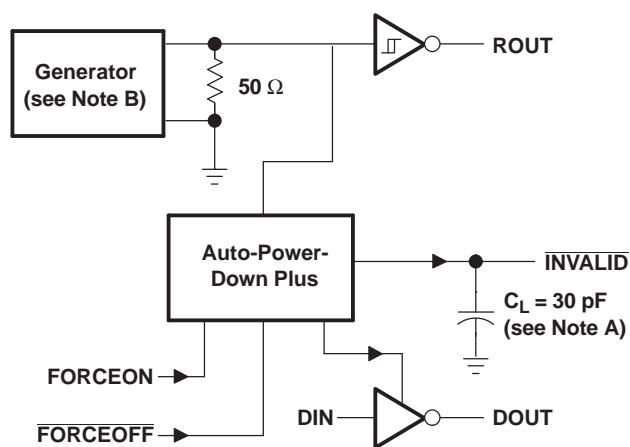
B. The pulse generator has the following characteristics: $Z_O = 50 \Omega$, 50% duty cycle, $t_r \leq 10 \text{ ns}$, $t_f \leq 10 \text{ ns}$.

Figure 3. Receiver Propagation Delay Times

PARAMETER MEASUREMENT INFORMATION



VOLTAGE WAVEFORMS



† Auto power down disables drivers and reduces supply current to 1 μ A.

Figure 4. **INVALID** Propagation Delay Times and Supply Enabling Time

PARAMETER MEASUREMENT INFORMATION

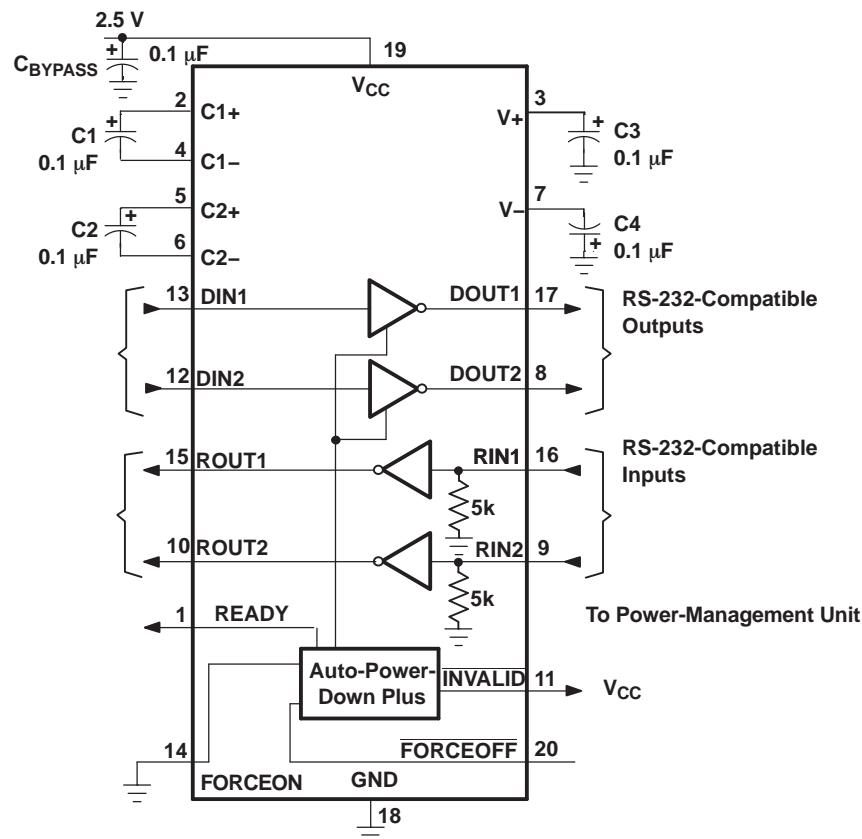


Figure 5. Typical Application Circuit

REVISION HISTORY

Changes from Original (June 2006) to Revision A	Page
• Updated document to new TI datasheet format - no specification changes.	1
• Removed Ordering Information Table.	2
• Updated TERMINAL FUNCTIONS table to fix inconsistency.	3

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
MAX3318ECPW	Obsolete	Production	TSSOP (PW) 20	-	-	Call TI	Call TI	0 to 70	MP318EC
MAX3318ECPWR	Obsolete	Production	TSSOP (PW) 20	-	-	Call TI	Call TI	0 to 70	MP318EC
MAX3318EIDB	Active	Production	SSOP (DB) 20	70 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	MP318EI
MAX3318EIDB.A	Active	Production	SSOP (DB) 20	70 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	MP318EI
MAX3318EIDBR	Active	Production	SSOP (DB) 20	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	MP318EI
MAX3318EIDBR.A	Active	Production	SSOP (DB) 20	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	MP318EI
MAX3318EIPW	Obsolete	Production	TSSOP (PW) 20	-	-	Call TI	Call TI	-40 to 85	MP318EI
MAX3318EIPWR	Active	Production	TSSOP (PW) 20	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	MP318EI
MAX3318EIPWR.A	Active	Production	TSSOP (PW) 20	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	MP318EI
MAX3318EIPWRG4	Active	Production	TSSOP (PW) 20	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	MP318EI
MAX3318EIPWRG4.A	Active	Production	TSSOP (PW) 20	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	MP318EI

⁽¹⁾ **Status:** For more details on status, see our [product life cycle](#).

⁽²⁾ **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

⁽³⁾ **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

⁽⁴⁾ **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

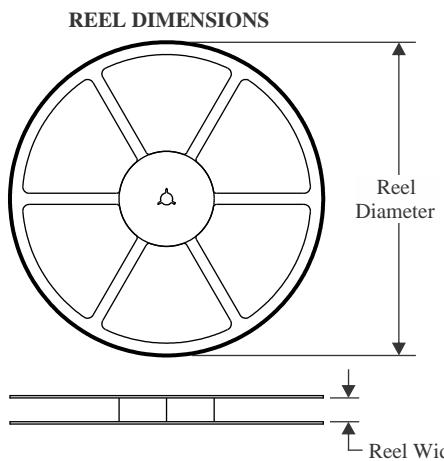
⁽⁵⁾ **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

⁽⁶⁾ **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

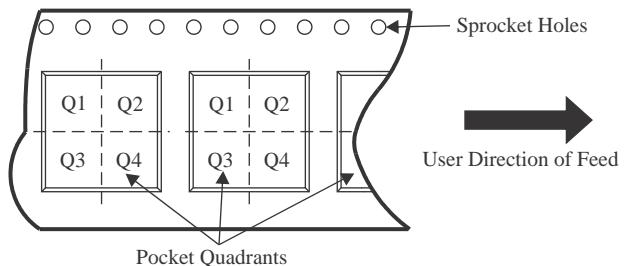
Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

TAPE AND REEL INFORMATION


A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE


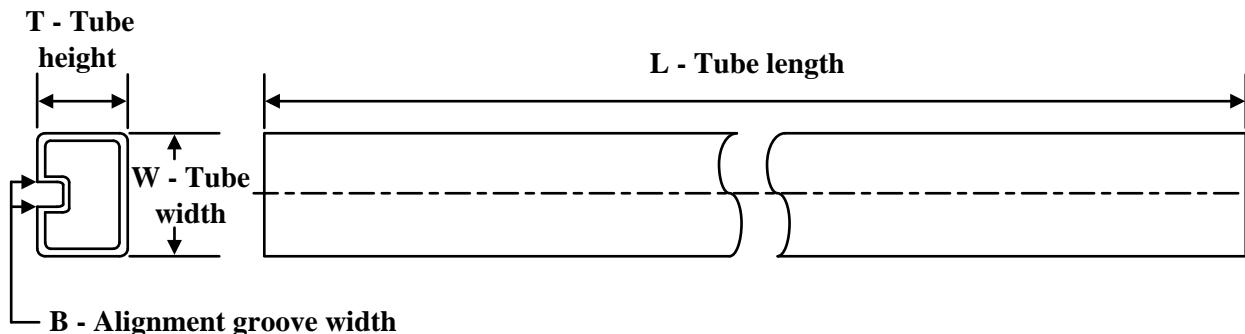
*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
MAX3318EIDBR	SSOP	DB	20	2000	330.0	16.4	8.2	7.5	2.5	12.0	16.0	Q1
MAX3318EIPWR	TSSOP	PW	20	2000	330.0	16.4	6.95	7.0	1.4	8.0	16.0	Q1
MAX3318EIPWRG4	TSSOP	PW	20	2000	330.0	16.4	6.95	7.0	1.4	8.0	16.0	Q1

TAPE AND REEL BOX DIMENSIONS


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
MAX3318EIDBR	SSOP	DB	20	2000	353.0	353.0	32.0
MAX3318EIPWR	TSSOP	PW	20	2000	353.0	353.0	32.0
MAX3318EIPWRG4	TSSOP	PW	20	2000	353.0	353.0	32.0

TUBE


*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (μ m)	B (mm)
MAX3318EIDB	DB	SSOP	20	70	530	10.5	4000	4.1
MAX3318EIDB.A	DB	SSOP	20	70	530	10.5	4000	4.1

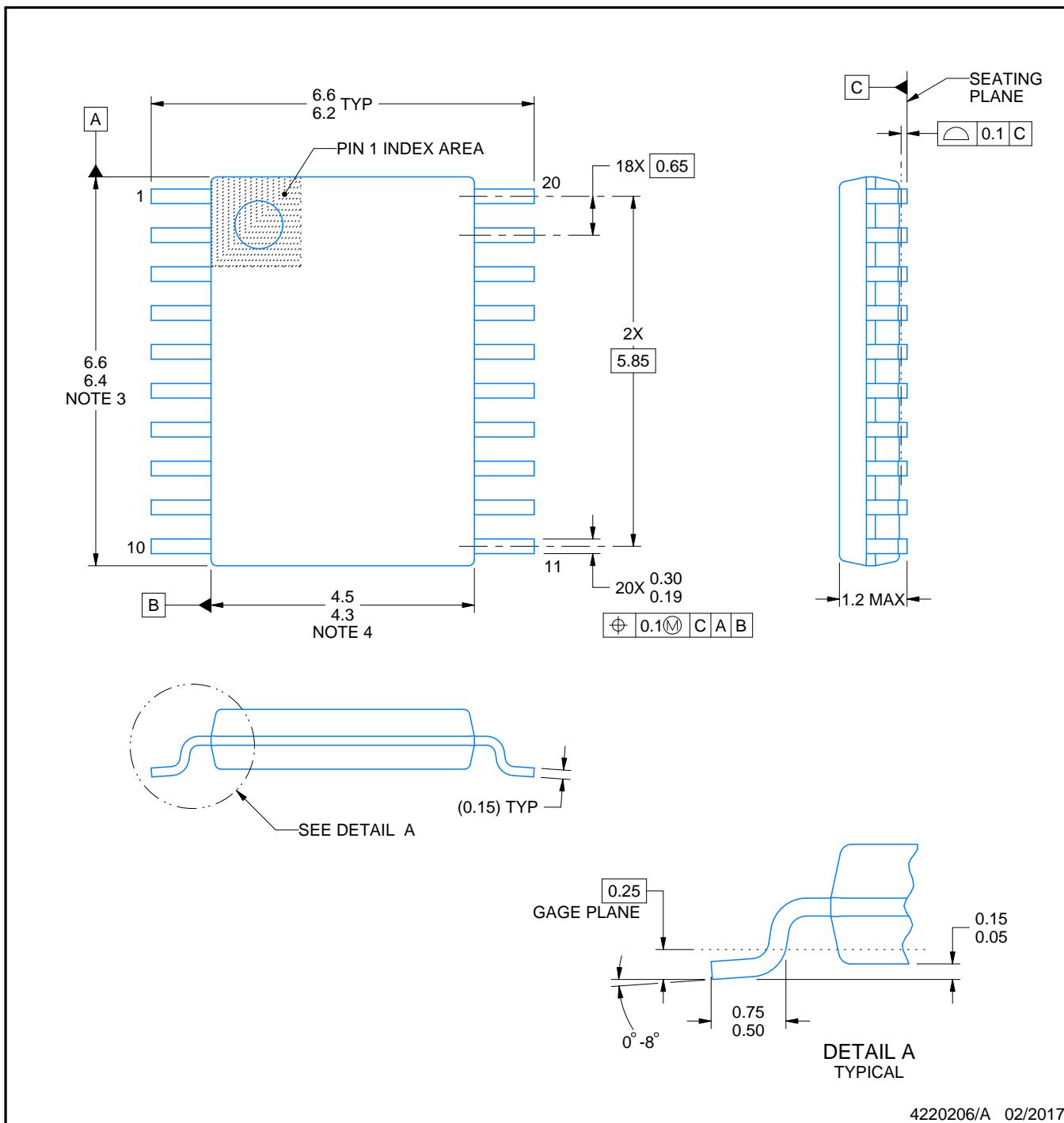
PACKAGE OUTLINE

PW0020A



TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



NOTES:

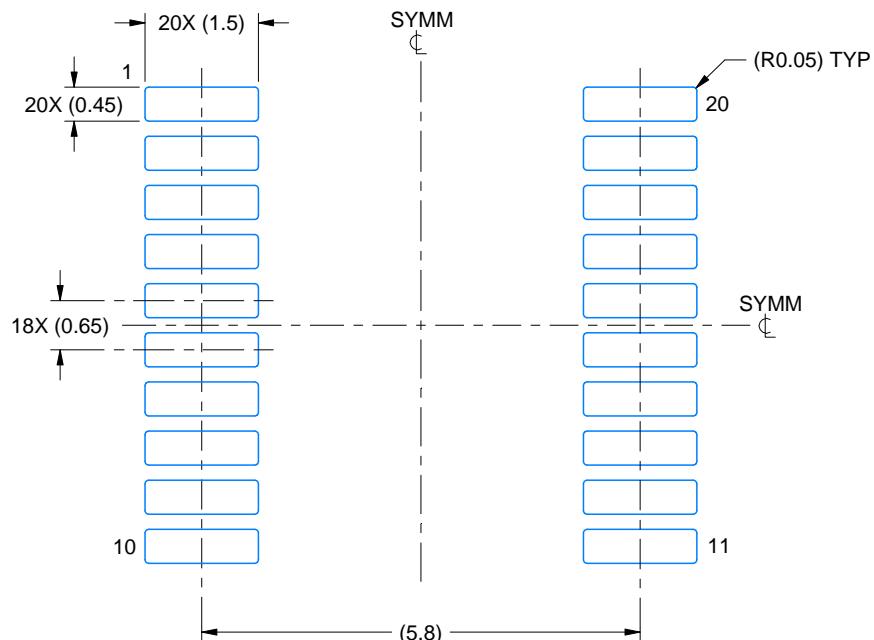
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-153.

EXAMPLE BOARD LAYOUT

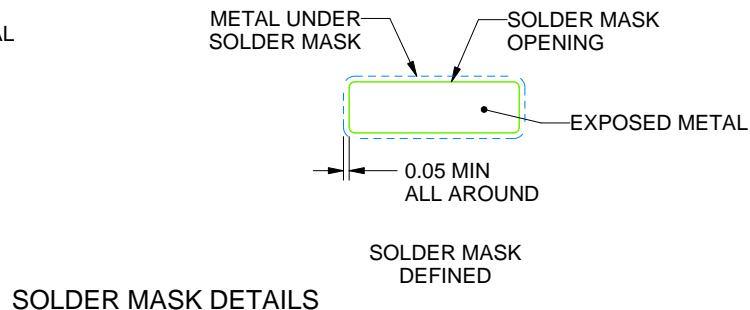
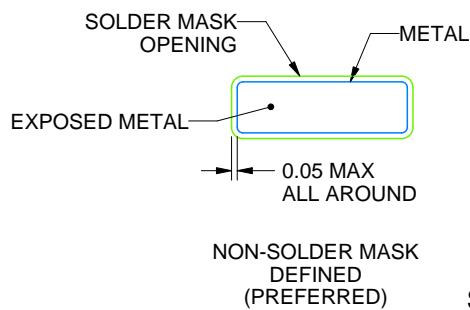
PW0020A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 10X



4220206/A 02/2017

NOTES: (continued)

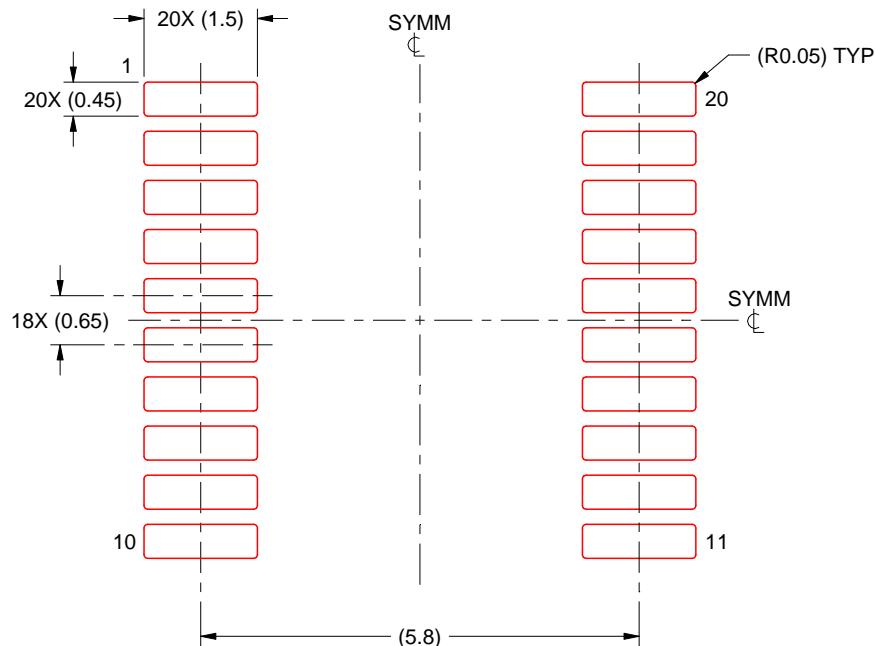
6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

PW0020A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE: 10X

4220206/A 02/2017

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

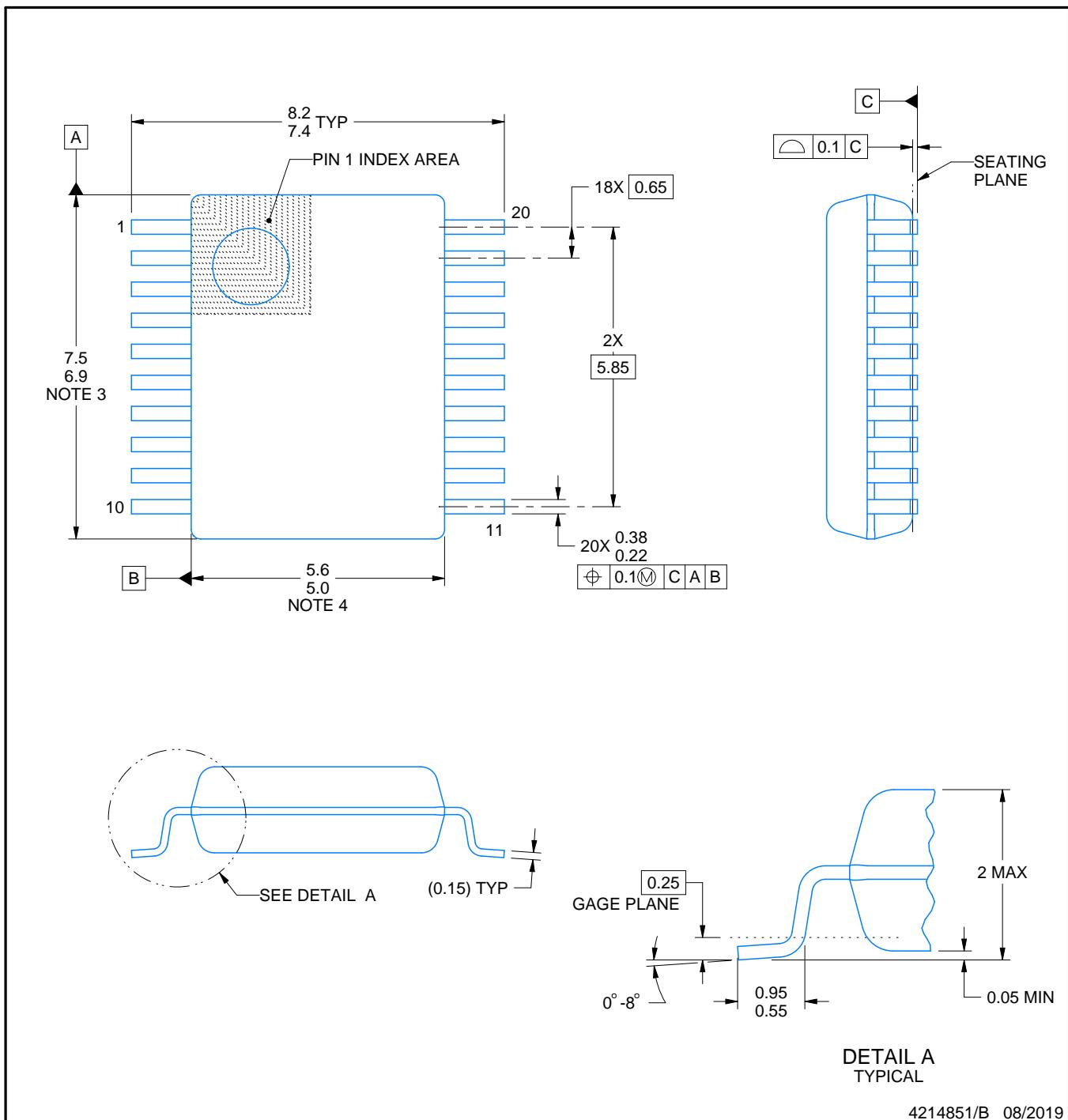
PACKAGE OUTLINE

DB0020A



SSOP - 2 mm max height

SMALL OUTLINE PACKAGE



NOTES:

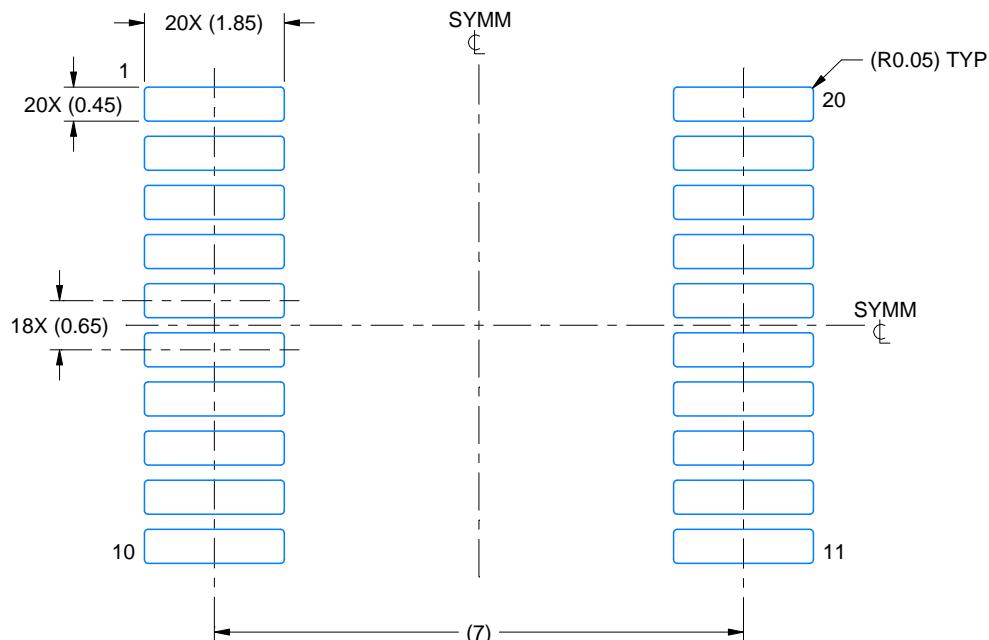
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-150.

EXAMPLE BOARD LAYOUT

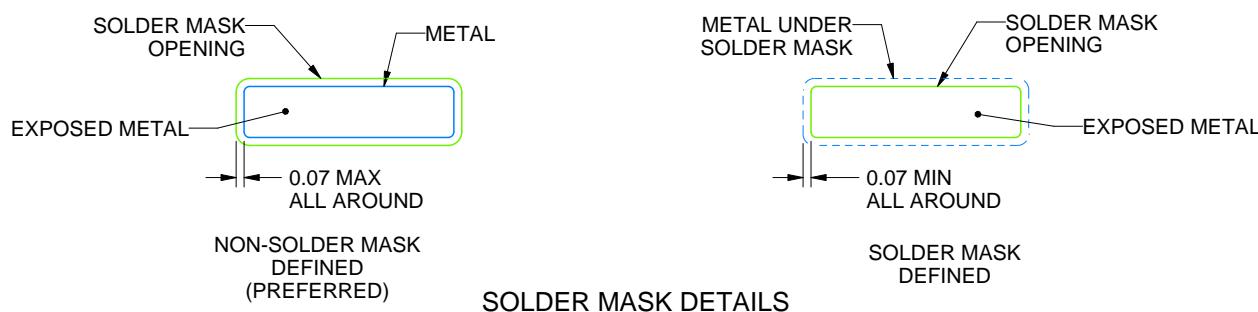
DB0020A

SSOP - 2 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 10X



4214851/B 08/2019

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

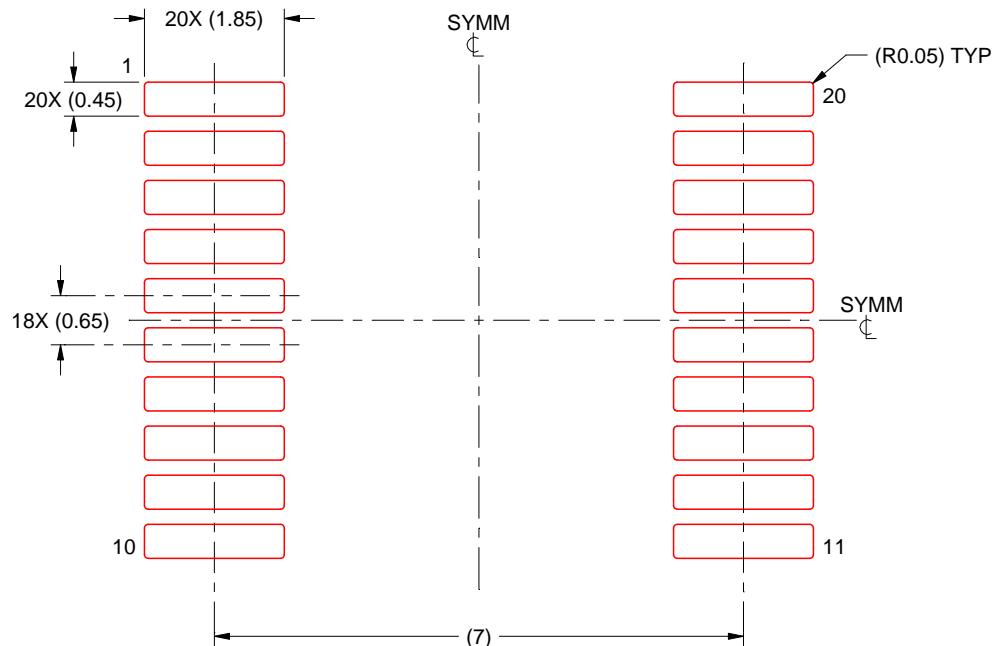
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

DB0020A

SSOP - 2 mm max height

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE: 10X

4214851/B 08/2019

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

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